## **SR-SCOPE® DMP30**

Built to last: Next level quality and durability thanks to all-aluminum housing

Full measuring control:

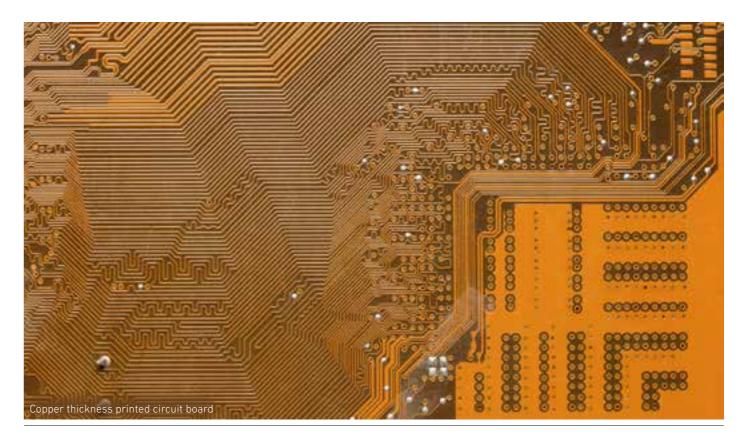
Feedback via light, sound and vibration whether measured values are within tolerance within tolerance

Perfect fit: Measure 24/7 due to quick and easy battery change

**Digital probe:** Fully digitized probe for the most demanding measurement tasks

Automatic device recognition, easy data export and comprehensive reporting





## First choice for copper thickness measurement

The SR-SCOPE® DMP30 from the DMP instrument family has been specially developed for measuring the copper thickness on the top side of printed circuit boards. It is ideal for spot-checking the copper thickness reliably in the production process, incoming or outgoing goods.

This robust handheld device uses the electrical 4-point resistance method in accordance with DIN EN 14571, making it well suited for measuring the thickness of thin copper layers on multi-layer boards or laminates. The other layers of the board or intermediate layers in the PCB, such as deeper insulating copper layers lying, have no influence on the measurement, so that the copper layer thickness can be determined precisely even with thin laminates. The SR-SCOPE® allows measurement in different coating thickness measurement ranges between 0.5 - 10 µm or 5 - 120 µm.

With the intuitive Tactile Suite, transferring, evaluating and exporting your measurement data is more comfortable than ever before.





Quick change battery

Special probes for different measurement ranges

## Features

- Robust and powerful handheld device for measuring copper thickness on printed circuit boards
- Test method: Microresistivity
- Measured value memory: 250,000 in 2,500 batches
- Measurement range: 0.5 10 μm or 5 120 μm
- Robust aluminum housing with protection class IP64
- Replaceable Li-ion battery for > 24 h operating time
- Easy data transfer via USB-C and Bluetooth
- Limit monitoring via light, sound and vibration
- Digital probe available